

DF005M - DF10M

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop, High Current Capability
- Surge Overload Rating to 50A Peak
- Designed for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- Lead Free Finish, RoHS Compliant (Date Code 0532+) (Note 3)

DF-M					
Dim	Min	Max			
Α	7.40	7.90			
В	6.20	6.50			
С	0.22	0.30			
D	1.27	2.03			
E	7.60	8.90			
G	3.81	4.69			
H	8.13	8.51			
J	2.40	3.40			
K	5.00	5.20			
L	0.46	0.58			
All Dimensions in mm					

Mechanical Data

Case: DF-M

- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Tin. Solder Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Polarity: As Marked on Case
- Marking Information: Type Number, See Page 3
- Weight: 0.38 grams (approximate)

Maximum Ratings and Electrical Characteristics

@T_A = 25°C unless otherwise specified

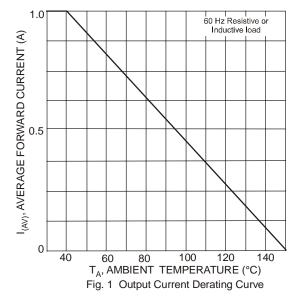
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

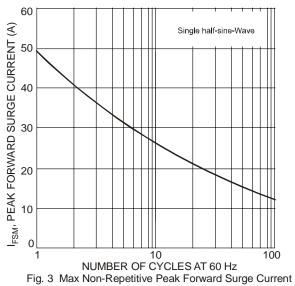
Characteristic		Symbol	DF 005M	DF 01M	DF 02M	DF 04M	DF 06M	DF 08M	DF 10M	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RMM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage		V_{RMS}	35	70	140	280	420	580	700	V
Average Rectified Output Current	@ T _A = 40°C	lo	1.0					Α		
Non-Repetitive Peak Forward Surge Current, 8.3 m Single Half Sine-Wave Superimposed on Rated Loa		I _{FSM}				50				Α
Forward Voltage (per element)	@ I _F = 1.0 A	V_{FM}	1.1			V				
Peak Reverse Current at Rated DC Blocking Voltage (per element)	@ T _A = 25°C @ T _A = 125°C	I _{RM}	10 500				μA			
I ² t Rating for Fusing (t<8.3ms)		l²t				10.4				A ² s
Typical Total Capacitance per element	(Note 1)	C _T	25			pF				
Typical Thermal Resistance, Junction to Ambient	(Note 2)	$R_{\theta JA}$	40				°C/W			
Operating and Storage Temperature Range		T _j , T _{STG}			-6	65 to +15	50			°C

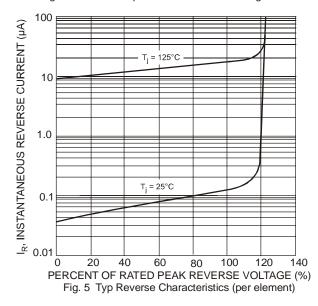
Notes:

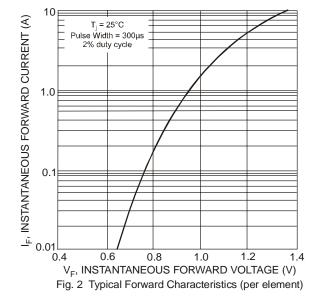
- 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
- ${\small 2.} \ \ \, \text{Thermal Resistance, junction to ambient, measured on PC board with } 5.0\text{mm}^2 \, (0.03\text{mm thick}) \, \text{land areas.}$
- 3. RoHS revision 13.2.2003. Glass and high temperature solder exemptions applied, see EU Directive Annex Notes 5 and 7.











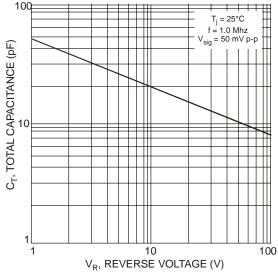


Fig. 4 Typical Total Capacitance (per element)



Ordering Information (Note 4)

Device*	Packaging	Shipping
DFxM	DF-M	Tube

^{*} x = Device type, e.g. DF005M or DF10M, etc.

Notes: 4. For packaging details, visit our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



⊇!! = Manufacturers' code marking XXXXX = Product type marking code, ex: DF10M YWW = Date code marking Y = Last digit of year ex: 2 for 2002 WW = Week code 01 to 52

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